



Material Content Data Sheet



Sales Product Name		BAS 40-02L E6327		Issued		1. August 2018		
MA#		MA001789470						
Package		PG-TSLP-2-1		Weight*		0.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.10		1041	
	noble metal	gold	7440-57-5	0.002	0.40		4037	
	inorganic material	silicon	7440-21-3	0.026	4.93	5.43	49285	54363
leadframe	non noble metal	nickel	7440-02-0	0.100	19.32	19.32	193175	193175
wire	noble metal	gold	7440-57-5	0.006	1.09	1.09	10939	10939
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		349	
	organic material	carbon black	1333-86-4	0.004	0.70		6986	
	plastics	epoxy resin	-	0.049	9.43		94308	
	inorganic material	silicondioxide	60676-86-0	0.310	59.70	69.86	596925	698568
leadfinish	noble metal	gold	7440-57-5	0.010	1.86	1.86	18587	18587
plating	noble metal	palladium	7440-05-3	0.003	0.58		5781	
	noble metal	gold	7440-57-5	0.010	1.86	2.44	18587	24368
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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